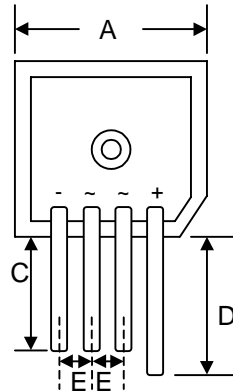


### Features

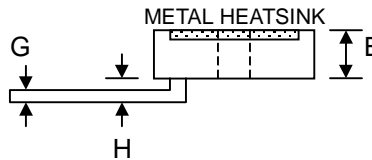
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space

### Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



KBPC-S		
Dim	Min	Max
A	28.40	28.70
B	10.97	11.23
C	13.90	—
D	19.10	—
E	5.10	—
G	1.20 Ø Typical	
H	3.05	3.60
All Dimensions in mm		



### Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristics	Symbol	-00GS	-01GS	-02GS	-04GS	-06GS	-08GS	-10GS	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$								V
Working Peak Reverse Voltage	$V_{RWM}$	50	100	200	400	600	800	1000	
DC Blocking Voltage	$V_R$								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_C = 55^\circ\text{C}$	$I_O$				15	25	35		A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$				300	300	400		A
Forward Voltage Drop (per element)	$V_{FM}$				1.1				V
Peak Reverse Current at Rated DC Blocking Voltage (per element)	$I_R$				5.0	500			$\mu\text{A}$
$I^2t$ Rating for Fusing ( $t < 8.3\text{ms}$ ) (Note 1)	$I^2t$				374	374	664		$\text{A}^2\text{s}$
Typical Thermal Resistance (per element) (Note 2)	$R_{\theta JC}$				2.0				K/W
RMS Isolation Voltage from Case to Lead	$V_{ISO}$				2500				V
Operating and Storage Temperature Range	$T_j, T_{STG}$				-65 to +150				$^\circ\text{C}$

Note: 1. Non-repetitive for  $t > 1\text{ms}$  and  $< 8.3\text{ms}$ .

2. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.

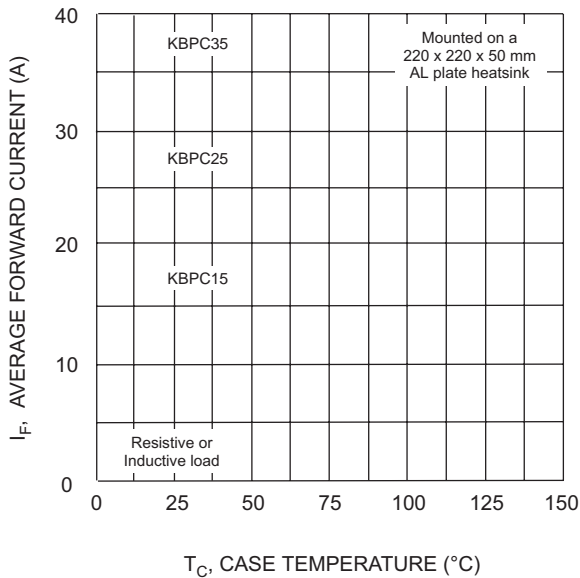


Fig. 1 Forward Current Derating Curve

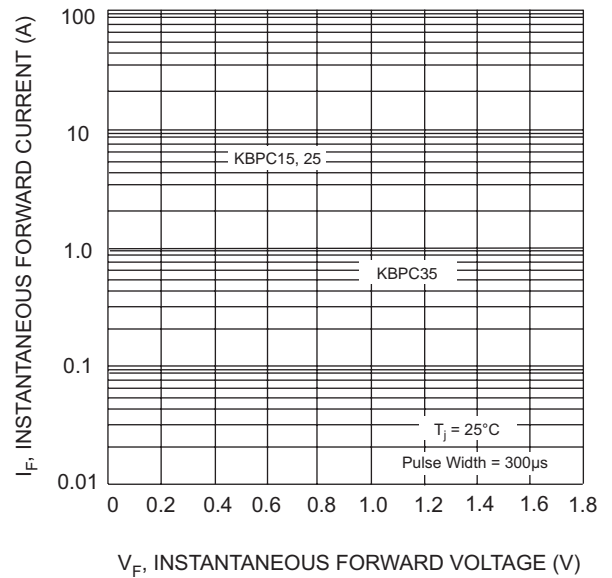


Fig. 2 Typical Forward Characteristics (per element)

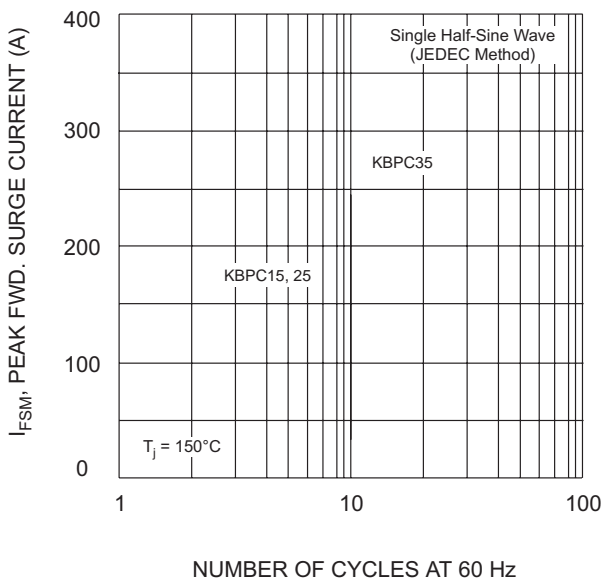


Fig. 3 Max Non-Repetitive Surge Current

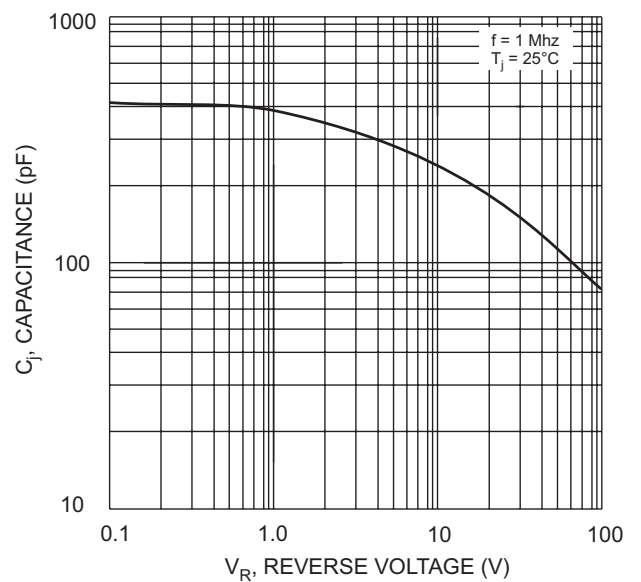


Fig. 4 Typical Junction Capacitance (per element)

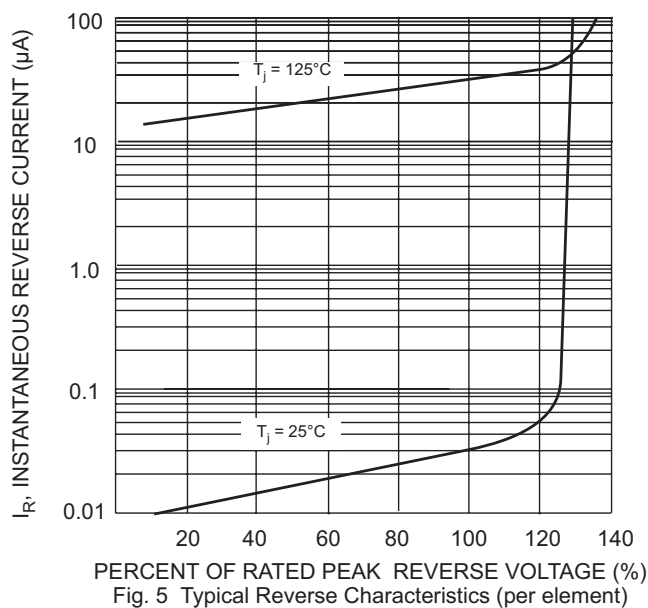


Fig. 5 Typical Reverse Characteristics (per element)

## ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
KBPCxx00GS	SIL Bridge	72 Units/Box
KBPCxx01GS	SIL Bridge	72 Units/Box
KBPCxx02GS	SIL Bridge	72 Units/Box
KBPCxx04GS	SIL Bridge	72 Units/Box
KBPCxx06GS	SIL Bridge	72 Units/Box
KBPCxx08GS	SIL Bridge	72 Units/Box
KBPCxx10GS	SIL Bridge	72 Units/Box

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

Won-Top Electronics Co., Ltd (WTE) has checked all information carefully and believes it to be correct and accurate. However, WTE cannot assume any responsibility for inaccuracies. Furthermore, this information does not give the purchaser of semiconductor devices any license under patent rights to manufacturer. WTE reserves the right to change any or all information herein without further notice.

**WARNING:** DO NOT USE IN LIFE SUPPORT EQUIPMENT. WTE power semiconductor products are not authorized for use as critical components in life support devices or systems without the express written approval.

**Won-Top Electronics Co., Ltd.**

No. 44 Yu Kang North 3rd Road, Chine Chen Dist., Kaohsiung, Taiwan

**Phone:** 886-7-822-5408 or 886-7-822-5410

**Fax:** 886-7-822-5417

**Email:** sales@wontop.com

**Internet:** <http://www.wontop.com>

*We power your everyday.*